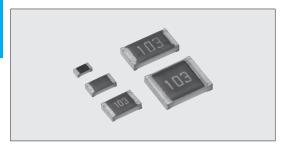
THICK FILM (ANTI SURGE)



SG73S Endured Surge Voltage Flat Chip Resistors



Coating color: Black (1E)

Green (1J, 2A, 2B, 2E)

■Features

- Superior to RK73 series chip resistors in surge withstanding voltage and high power.
- Resistance tolerance is available from $\pm 0.5\%$.
- Suitable for both reflow and flow solderings.
- Products with lead free termination meet EU-RoHS requirements. EU-RoHS regulation is not intended for Pb-glass contained in electrode, resistor element and glass.
- AEC-Q200 Tested.

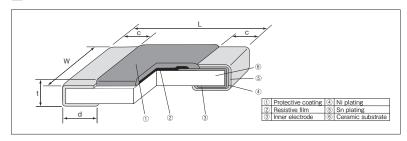
Applications

- E.C.U.
- Circuits to catch inductive lighting surge.

■Reference Standards

IEC 60115-8 JIS C 5201-8 EIAJ RC-2134C

Construction

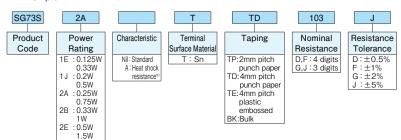


■Dimensions

Туре		Weight(g)					
(Inch Size Code)	L	W	С	d	t	(1000pcs)	
1E (0402)	1.0+0.1	0.5±0.05	0.15±0.1	$0.25^{+0.05}_{-0.1}$	0.35±0.05	0.68	
1J (0603)	1.6±0.2	0.8±0.1	0.3±0.1	0.3±0.1	0.45±0.1	2.14	
1J AT (0603)	1.6±0.2		0.35±0.15	0.5±0.2	0.45±0.1		
2A (0805)	2.0±0.2	1.25±0.1	0.3+0.2	$0.3^{+0.2}_{-0.1}$	0.5±0.1	4.54	
2A AT (0805)	2.0±0.2	1.25±0.1	0.45±0.25	0.6±0.2	0.55±0.1		
2B (1206)		1.6±0.2	0.4 ^{+0.2}	$0.4^{+0.2}_{-0.1}$		9.14	
2B AT (1206)	3.2±0.2	1.6±0.2	0.55±0.35	0.8±0.2	0.6±0.1	9.14	
2E (1210)		2.6±0.2	0.4+0.2	0.4+0.2]	15.5	

■Type Designation

Example



 $\ensuremath{\%1}$ 1J, 2A, and 2B are available for Heat shock resistance.

No resistance marking.

Contact us when you have control request for environmental hazardous material other than the substance specified by EU-RoHS.

For further information on taping, please refer to APPENDIX C on the back pages.

Ratings

		Datad	Datad	T.C.R.	Resistance Range (Ω)			Max.	Max.			
Type Power Rating		ating Ambient	Rated Terminal	(×10 ⁻⁶ / K)	D:±0.5%	F:±1%	G:±2% J:±5%	Working	Overload	Packaging & Q' ty/Reel (pcs)		
	Temp.	Part Temp.	(N	E24 · E96	E24 · E96	E24	Voltage	Voltage	TP	TD	TE	
1E	0.125W	70°C	125℃	±200) 10~1M 1~	1~1M 1~10M	1. 1014	75V	100V	10,000		
I NEV	₽ 0.33W	_	105℃]			/5/	1000	10,000	_		
	0.2W 70°C			±100	510~576k	510~576k	510~560k	150V	200V	10,000*4	5,000	_
		70°C	135℃	±100*2	10~499	1~499	1~470					
1J					590k~1M	590k~1M	620k~10M					
13	NEW 0.5W	_ 1		±100	510~576k	510~576k	510~560k					
NEV			105℃	±100*2	10~499	1~499	1~470					
				±100	590k~1M	590k~1M	620k~10M					
2A	0.25W	70°C	125℃	±200	10~1M 1~1M 1~	1~1M 1~10M	400V	600V	10,000*4	5,000	4.000**4	
ZA NEV	0.75W	_	105℃			11001 4001	(800V)*3	10,000	3,000	4,000		
2B	0.33W	70°C	125℃	±200	10~1M 1~	1~1M	1~10M	200V	400V	_	5,000	4,000**4
NEV	V 1.0W	_	105℃			1 - 1101	1.010101	2000				
2E	0.5W	70°C	125℃	+000	101M	11 M	1~10M	200V	400\/		5,000	4,000**4
ZE NEV	V1.5W	_	105℃	±200	10~1M	1~1M	1,~10101	2007	400V	_	5,000	4,000**

Operating Temperature Range : $-55^{\circ}\text{C} \sim +155^{\circ}\text{C}$

Rated voltage=√Power Rating×Resistance value or Max. working voltage, whichever is lower.

 $\ensuremath{\text{\%}}\xspace 2$ Cold T.C.R. $(-55\ensuremath{\text{\%}}\xspace \sim +25\ensuremath{\text{\%}}\xspace)$ is $\pm 150 \times 10^{-6} / K$.

*3 Applies when power rating is 0.4W or lower.

*4 Standard packaging : TD(4mm pitch punch paper)

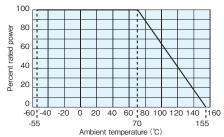
If any questions arise whether to use the "Rated Ambient Temperature" or the "Rated Terminal Part Temperature" in your usage conditions, please give priority to the "Rated Terminal Part Temperature".

For more details, please refer to "Introduction of the derating curves based on the terminal part temperature" on the beginning of our catalog.



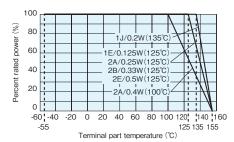
Derating Curve

Ambient temperature

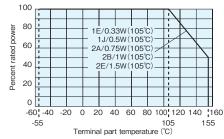


For resistors operated at an ambient temperature of $70^\circ\!\mathrm{C}$ or higher, the power shall be derated in accordance with the above derating

Terminal part temperature



Terminal part temperature

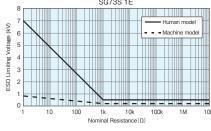


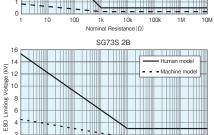
When the terminal part temperature of the resistor exceeds the rated terminal part temperature shown above, the power shall be derated according to the derating curve.

If you want to use at the rated power of **3, please use the derating curves based on the terminal part temperature of the center graph.

**Please refer to "Introduction of the derating curves based on the terminal part temperature" on the beginning of our catalog before use.

■ESD Limiting Voltage

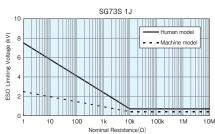


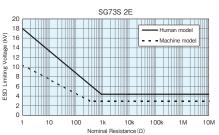


10k

Nominal Resistance(0)

100k 1M

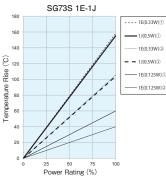


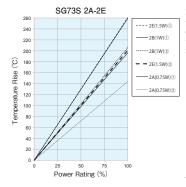


SG73S 2A Limiting Voltage (kV) - Machine model ESD 10 100 1k 10k 100k 1 M ance(Ω)

10 ■Temperature Rise

100





Regarding the temperature rise, the value of the temperature varies per conditions and board for use since the temperature is measured under our measuring conditions.

ture: 25°C PCB: FR-4 t = 1.6n

■Performance

Test Items	Performance Requirements ΔR±	(%+0.1Ω)	Teet Methodo					
restitems	Limit	Typical	Test Methods					
Resistance	Within specified tolerance	_	25°C					
T.C.R.	Within specified T.C.R.	_	+25°C/-55°C and +25°C/+125°C					
			Overload for 5s					
Overload (Short time)	2	0.5	Type 1E 1J 2A 2B 2E					
			Overload 1.25W 2.063W 2W (1.6W**3) 3W 4W					
Resistance to	1	0.75	260°C±5°C, 10s±1s					
soldering heat	<u> </u>	0.73						
Rapid change of	0.5: Characteristic [Nil] (Standard)	0.3: Characteristic [Nil] (Standard)	Characteristic [Nil] (Standard) : -55°C (30min.) /+125°C (30min.) 100 cycles					
temperature	1: Characteristic [A] (Heat shock resistance)	0.5: Characteristic [A] (Heat shock resistance)	Characteristic [A] (Heat shock resistance) : −55°C (30min.) /+125°C (30min.) 1000 cycles					
Moisture resistance	3	0.75	40°C±2°C, 90%~95%RH, 1000h					
Moisture resistance	S	0.75	1.5h ON/0.5h OFF cycle					
Endurance at 70°C or rated	3 0.75		70°C±2°C or rated terminal part temperature ±2°C 1000h					
terminal part temperature	3	0.75	1.5h ON/0.5h OFF cycle					
High temperature exposure	1	0.3	+155°C 1000h					

■Precautions for Use

• The substrate of chip resistors is alumina. Cracks may occur at the connection of solder (solder fillet portion) due to the difference of the coefficient of thermal expansion from a mounting board when heat stress like heat cycle, etc. are repeatedly given to them. Care should be taken to the occurrence of the cracks when the change in ambient temperature or ON/OFF of load is repeated. The occurrence of the crack by heat stress may be influenced by the size of a pad, solder volume, heat radiation of mounting board etc., so please pay careful attention to designing when a big change in ambient temperature and conditions for use like ON/OFF of load can be assumed.